

**AMENDMENT TRANSMITTAL LETTER**Docket No.
TESSERA 3.0-139 DIVApplication No.
09/854,269Filing Date
May 11, 2001Examiner
Monica LewisArt Unit
2822

Applicant(s): Thomas H. DiStefano

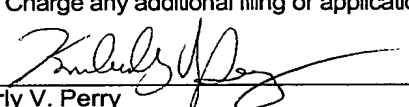
Invention: MICROELECTRONIC PACKAGES WITH ELONGATED SOLDER INTERCONNECTIONS

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	7	- 20 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

☒ Large Entity☐ Small Entity☒ No additional fee is required for this amendment.☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.☐ Payment by credit card. Form PTO-2038 is attached.☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 12-1095
as described below. A duplicate copy of this sheet is enclosed.☒ Credit any overpayment.☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.
Kimberly V. Perry
Attorney Reg. No.: 43,612

Dated: November 7, 2002

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: November 7, 2002

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(Kimberly V. Perry)



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Dated: November 7, 2002 Signature: Kimberly V. Perry

(Kimberly V. Perry)

Docket No.: TESSERA 3.0-139 DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Thomas H. DiStefano

Application No.: 09/854,269

Filed: May 11, 2001

For: MICROELECTRONIC PACKAGES WITH
ELONGATED SOLDER
INTERCONNECTIONS

Commissioner for Patents
Washington, DC 20231

Group Art Unit: 2822

Examiner: *Monica Lewis*

*5# and a
drug corrections*

*11/25/02
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AMENDMENT

Dear Madam:

In response to the Official Action mailed May 2002, in which claims 1-7 were rejected, applicants submit the following amendments and remarks.

IN THE TITLE

CLEAN COPY OF AMENDED TITLE:

MICROELECTRONIC PACKAGES WITH ELONGATED SOLDER
INTERCONNECTIONS

IN THE DRAWINGS

Please amend Figs. 5, 11 and 13 as shown in the attached red-lined drawings.

IN THE CLAIMS

CLEAN COPY OF AMENDED CLAIMS:

a *sub B1* 1. (Amended) A packaged microelectronic element comprising:

(a) a microelectronic element having a front surface with contact pads thereon;